

# AP4606B

## N and P-Channel Enhancement Mosfet

### Feature

- **N-Channel**

$V_{DD}=30V, I_D=7A$

$R_{DS(ON)} < 25m\Omega @ V_{GS}=10V$  TYP:18 mΩ

$R_{DS(ON)} < 38m\Omega @ V_{GS}=4.5V$  TYP:25 mΩ

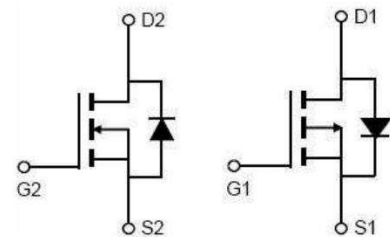
- **P-Channel**

$V_{DD}=-30V, I_D=-5.1A$

$R_{DS(ON)} < 50m\Omega @ V_{GS}=-10V$  TYP:38 mΩ

$R_{DS(ON)} < 70m\Omega @ V_{GS}=-4.5V$  TYP:53 mΩ

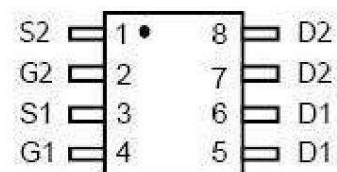
- Lead free product is acquired
- High power and current handling capability
- Surface mount package



N-channel

P-channel

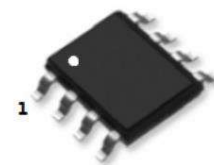
Schematic diagram



Marking and pin assignment

### Application

- PWM applications
- Load Switch
- Power management



SOP-8

### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity (PCS)
4606B	AP4606B	SOP-8	13 inch	-	4000

### ABSOLUTE MAXIMUM RATINGS ( $T_a=25^\circ C$ unless otherwise noted)

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	$V_{DS}$	30	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	$\pm 20$	V
Continuous Drain Current ( $T_a = 25^\circ C$ )	$I_D$	7	-5.1	A
Continuous Drain Current ( $T_a = 100^\circ C$ )	$I_D$	4.5	-3.3	A
Pulsed Drain Current <sup>(1)</sup>	$I_{DM}$	28	-20.4	A
Power Dissipation	$P_D$	2.15	2.15	W
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	58	58	$^\circ C/W$
Junction Temperature	$T_J$	150	150	$^\circ C$
Storage Temperature	$T_{STG}$	-55~ +150	-55~ +150	$^\circ C$

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# AIIPOWER

## DATA SHEET

### N-CH ELECTRICAL CHARACTERISTICS( $T_a=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	30			V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 30V, V_{GS} = 0V$			1	$\mu A$
Gate-body leakage current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 100$	nA
Gate threshold voltage <sup>(2)</sup>	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1	1.5	2.5	V
Drain-source on-resistance <sup>(2)</sup>	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 5A$		18	25	m $\Omega$
		$V_{GS} = 4.5V, I_D = 3A$		25	38	
<b>Dynamic characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 15V, V_{GS} = 0V, f = 1MHz$		490		pF
Output Capacitance	$C_{oss}$			79		
Reverse Transfer Capacitance	$C_{rss}$			61		
<b>Switching characteristics</b>						
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 15V, I_D = 3A, R_L = 6\Omega$ $V_{GS} = 10V, R_G = 3\Omega$		4.5		ns
Turn-on rise time	$t_r$			2.5		
Turn-off delay time	$t_{d(off)}$			14.5		
Turn-off fall time	$t_f$			3.5		
Total Gate Charge	$Q_g$	$V_{DS} = 15V, I_D = 5A,$ $V_{GS} = 10V$		5.2		nC
Gate-Source Charge	$Q_{gs}$			0.9		
Gate-Drain Charge	$Q_{gd}$			1.3		
<b>Source-Drain Diode characteristics</b>						
Diode Forward voltage <sup>(2)</sup>	$V_{DS}$	$V_{GS} = 0V, I_S = 7A$			1.2	V
Diode Forward current <sup>(3)</sup>	$I_S$		-	-	7	A

P-CH ELECTRICAL CHARACTERISTICS( $T_a=25^{\circ}\text{C}$  unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-30			V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = -30V, V_{GS} = 0V$			1	$\mu A$
Gate-body leakage current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 100$	nA
Gate threshold voltage <sup>(2)</sup>	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1	-1.5	-2.5	V
Drain-source on-resistance <sup>(2)</sup>	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -4A$		38	50	m $\Omega$
		$V_{GS} = -4.5V, I_D = -3A$		53	70	
<b>Dynamic characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = -15V, V_{GS} = 0V, f = 1MHz$		580		pF
Output Capacitance	$C_{oss}$			98		
Reverse Transfer Capacitance	$C_{rss}$			74		
<b>Switching characteristics</b>						
Turn-on delay time	$t_{d(on)}$	$V_{DD} = -15V, I_D = -1A, R_L = 6\Omega$ $V_{GS} = -10V, R_G = 1\Omega$		14		ns
Turn-on rise time	$t_r$			61		
Turn-off delay time	$t_{d(off)}$			19		
Turn-off fall time	$t_f$			10		
Total Gate Charge	$Q_g$	$V_{DS} = -15V, I_D = -4.1A,$ $V_{GS} = -10V$		6.8		nC
Gate-Source Charge	$Q_{gs}$			1		
Gate-Drain Charge	$Q_{gd}$			1.4		
<b>Source-Drain Diode characteristics</b>						
Diode Forward voltage <sup>(2)</sup>	$V_{DS}$	$V_{GS} = 0V, I_S = -4A$			1.2	V
Diode Forward current <sup>(3)</sup>	$I_S$		-	-	-5.1	A

**Notes:**

1. Repetitive Rating: pulse width limited by maximum junction temperature
2. Pulse Test: pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
3. Surface Mounted on FR4 Board,  $t \leq 10$  sec

**N Test Circuit**

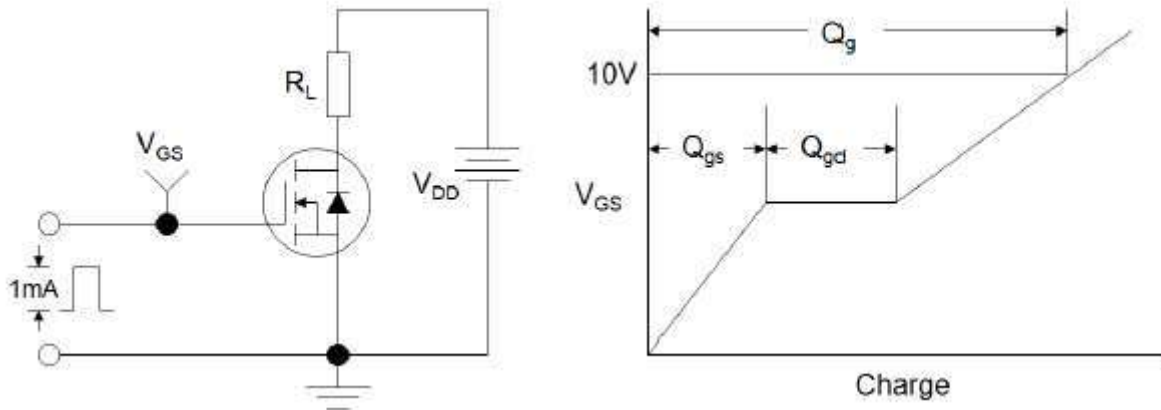


Figure1:Gate Charge Test Circuit & Waveform

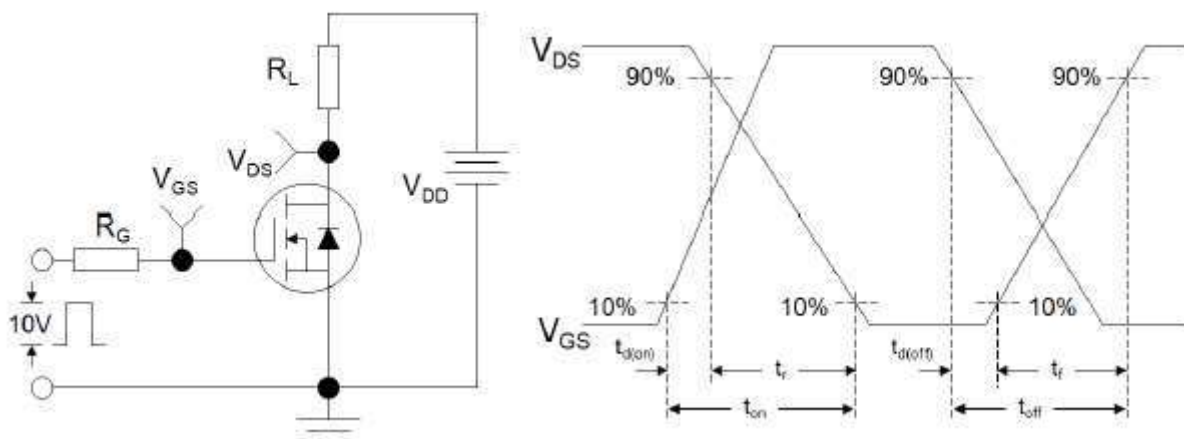


Figure 2: Resistive Switching Test Circuit & Waveforms

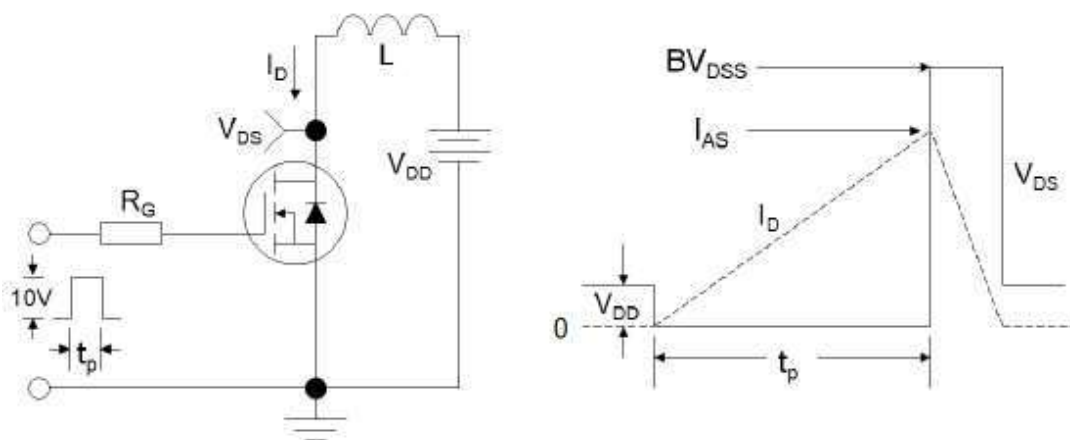
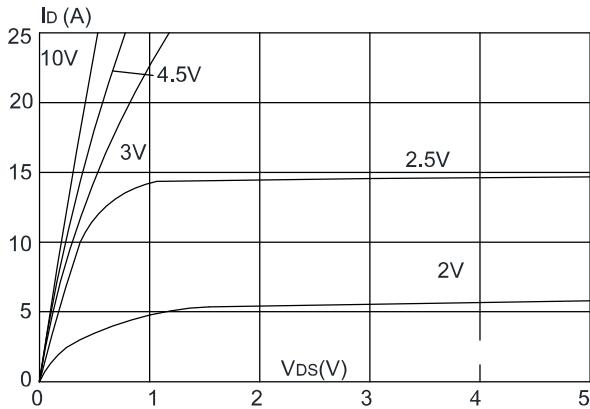
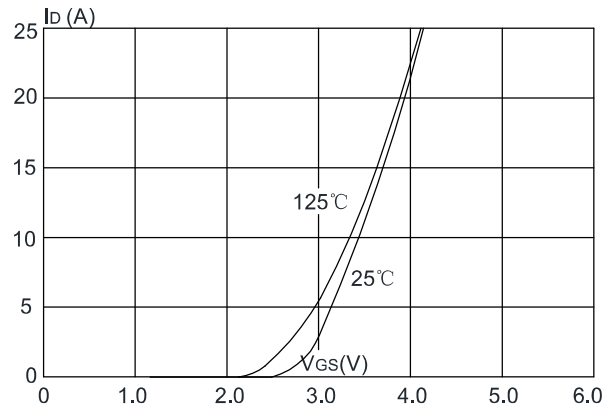


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

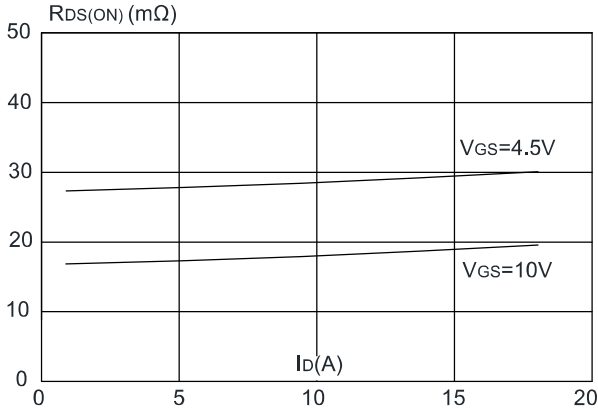
**Figure 1: Output Characteristics**



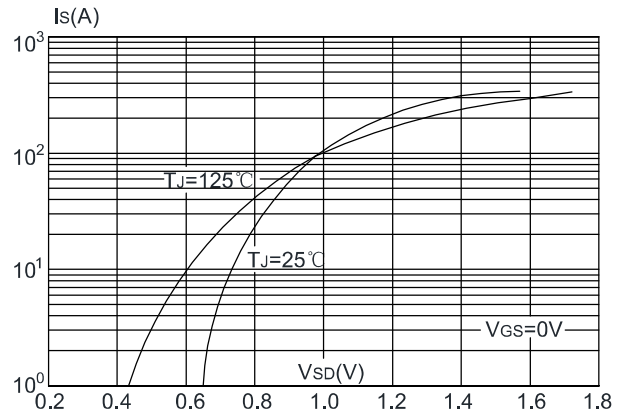
**Figure 2: Typical Transfer Characteristics**



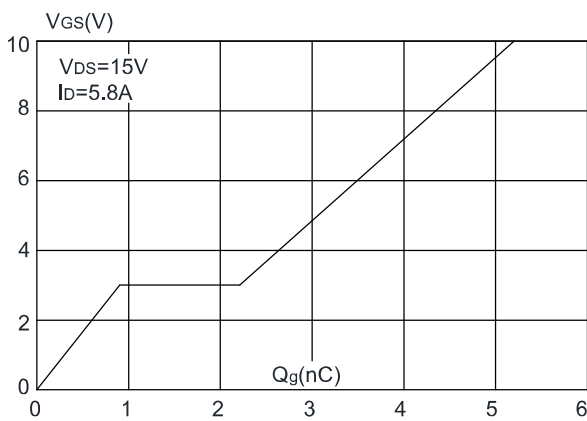
**Figure 3: On-resistance vs. Drain Current**



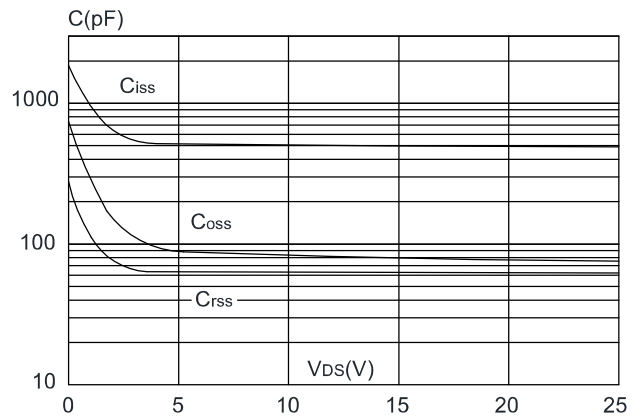
**Figure 4: Body Diode Characteristics**



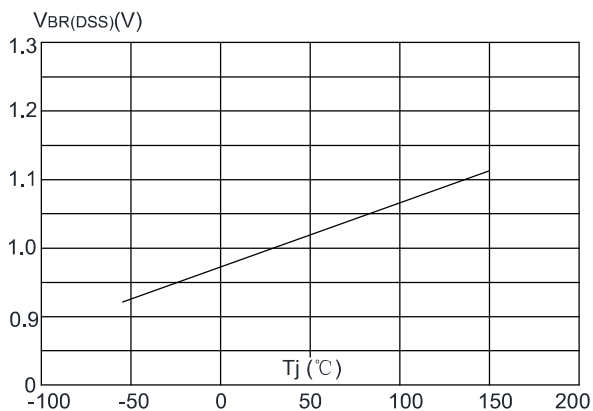
**Figure 5: Gate Charge Characteristics**



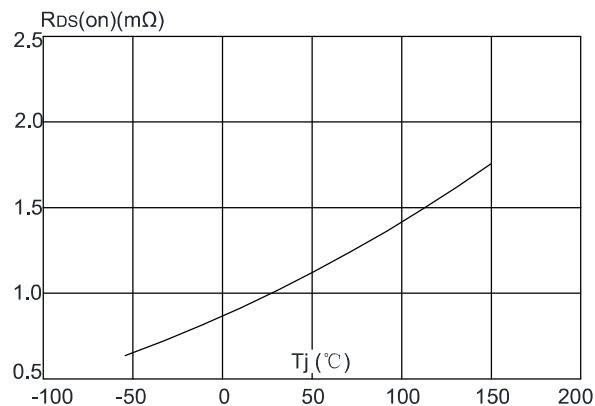
**Figure 6: Capacitance Characteristics**



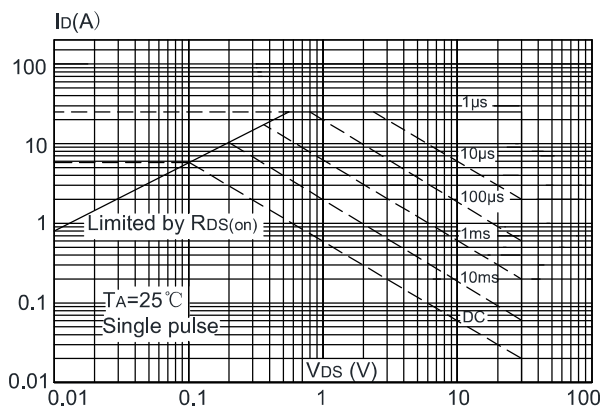
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



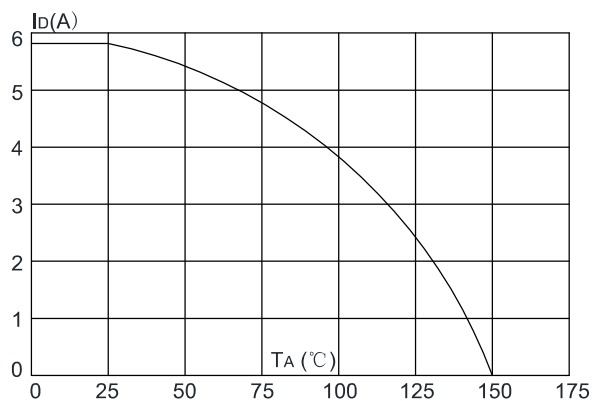
**Figure 8:** Normalized on Resistance vs. Junction Temperature



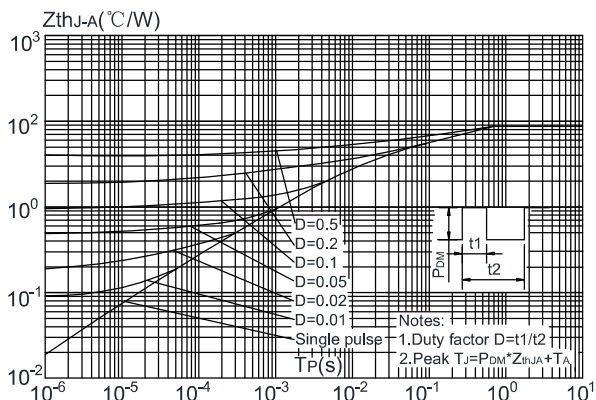
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature

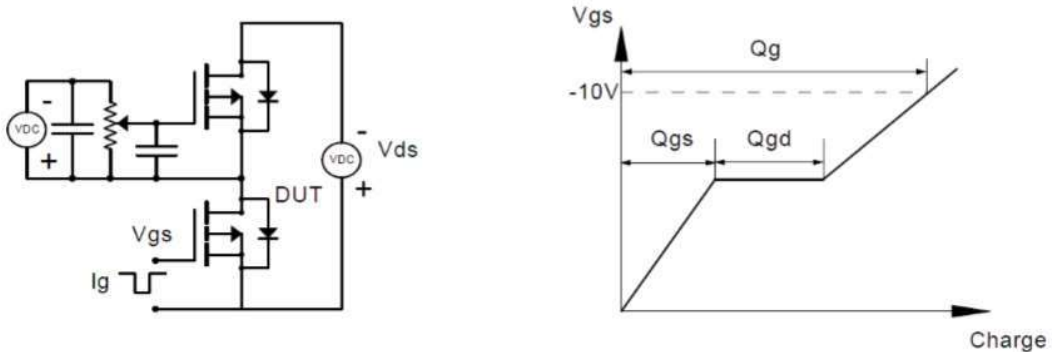


**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

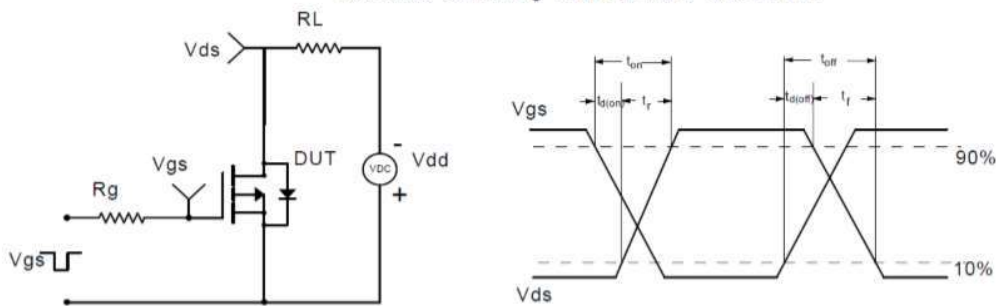


**P Typical Performance Characteristics**

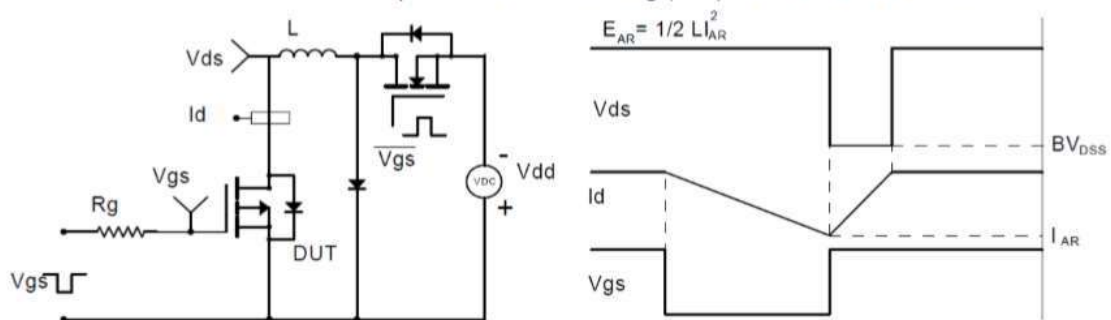
Gate Charge Test Circuit & Waveform



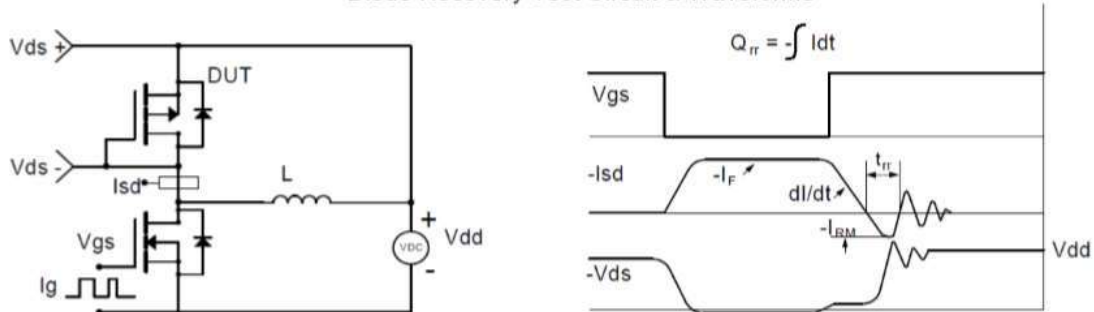
Resistive Switching Test Circuit & Waveforms



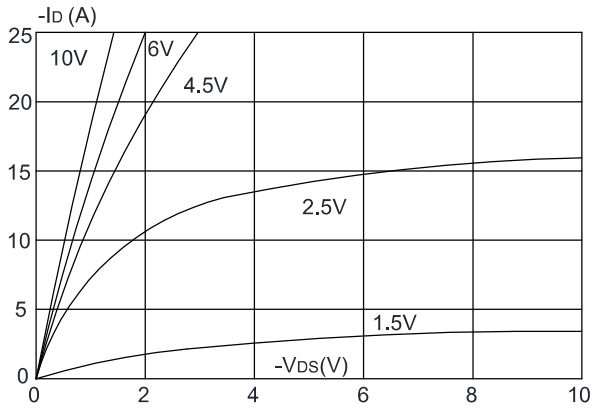
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



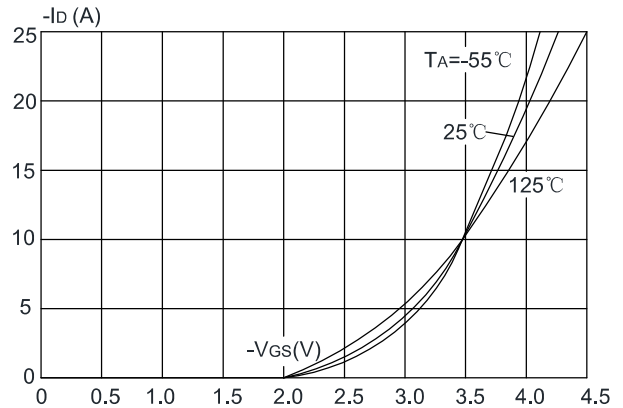
Diode Recovery Test Circuit & Waveforms



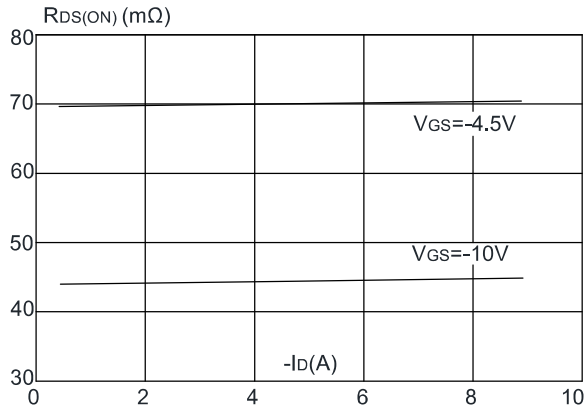
**Figure 1: Output Characteristics**



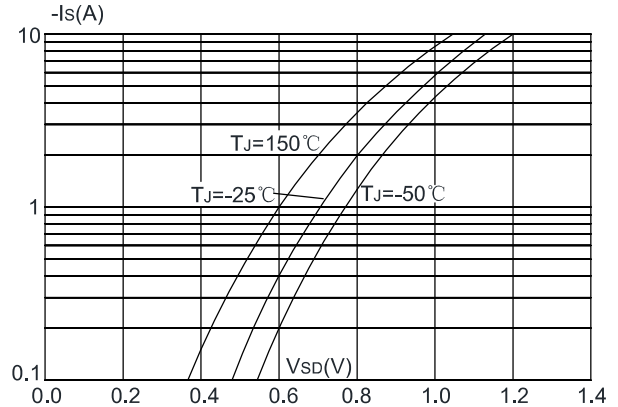
**Figure 2: Typical Transfer Characteristics**



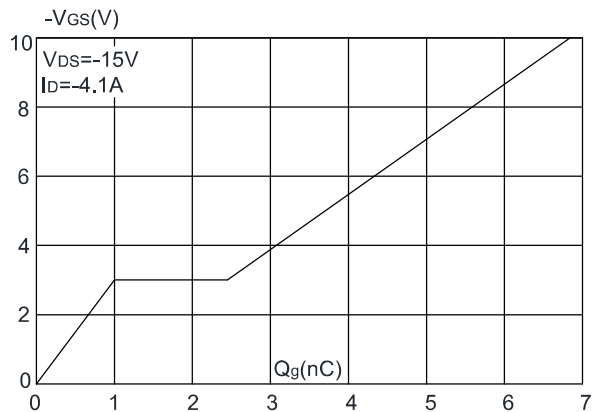
**Figure 3: On-resistance vs. Drain Current**



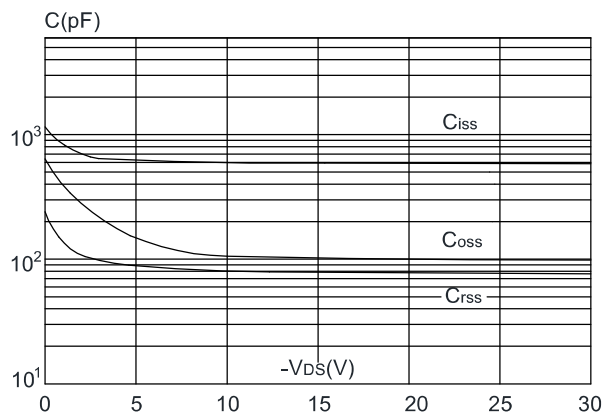
**Figure 4: Body Diode Characteristics**



**Figure 5: Gate Charge Characteristics**

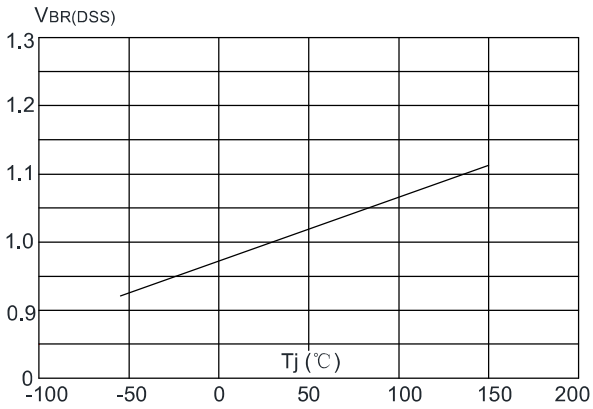


**Figure 6: Capacitance Characteristics**

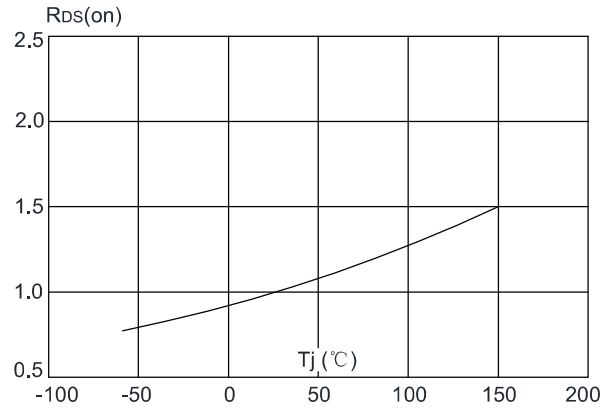




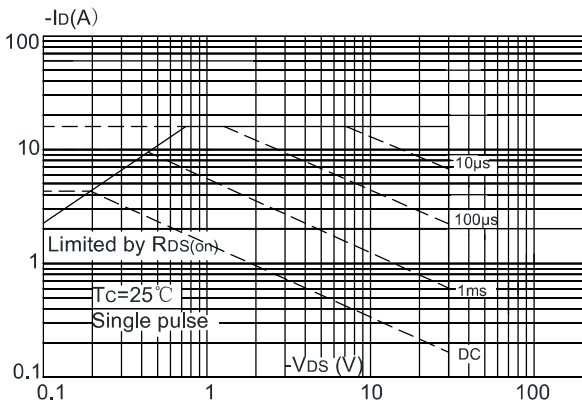
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



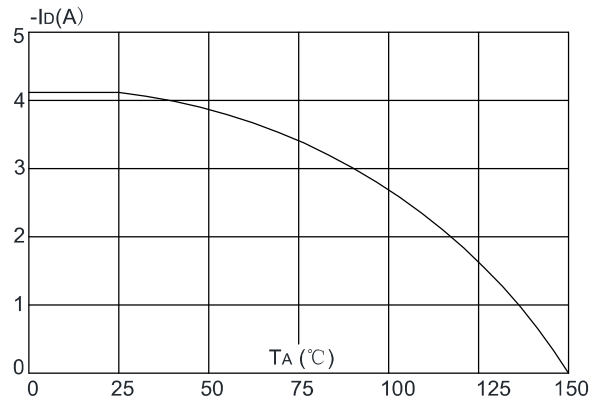
**Figure 8:** Normalized on Resistance vs. Junction Temperature



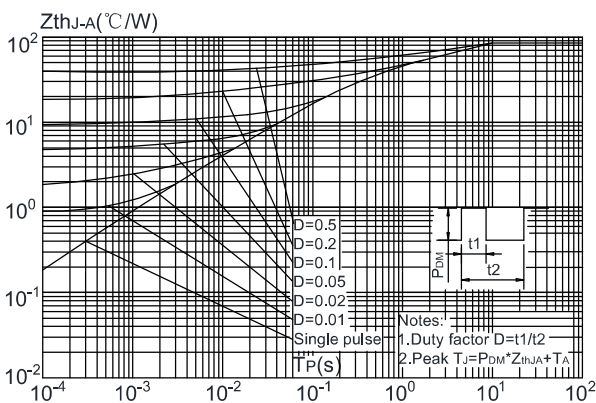
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature



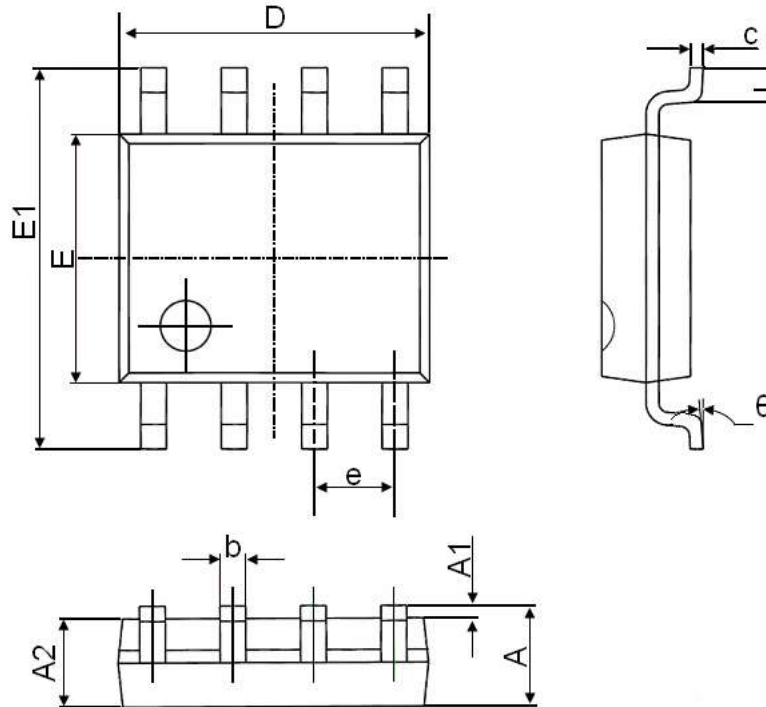
**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



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### SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
theta	0°	8°	0°	8°